

# **Low V<sub>CE(sat)</sub> PNP Transistors** 60 V, 1 A

## **NSS60100DMT**

onsemi's e<sup>2</sup>PowerEdge family of low V<sub>CE(sat)</sub> transistors are miniature surface mount devices featuring ultra low saturation voltage (V<sub>CE(sat)</sub>) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and LED lightning, power management...etc. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### **Features**

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- NSV60100DMTWTBG Wettable Flanks Device
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

| Rating                         | Symbol          | Max | Unit |
|--------------------------------|-----------------|-----|------|
| Collector-Emitter Voltage      | $V_{CEO}$       | 60  | Vdc  |
| Collector-Base Voltage         | $V_{CBO}$       | 60  | Vdc  |
| Emitter-Base Voltage           | $V_{EBO}$       | 6   | Vdc  |
| Collector Current - Continuous | Ic              | 1   | Α    |
| Collector Current - Peak       | I <sub>CM</sub> | 2   | Α    |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

| Characteristic   | Symbol                            | Max            | Unit |
|--|-----------------------------------|----------------|------|
| Thermal Resistance Junction-to-Ambient (Notes 1 and 2)               | $R_{\theta JA}$                   | 55             | °C/W |
| Total Power Dissipation per Package @ T <sub>A</sub> = 25°C (Note 2) | P <sub>D</sub>                    | 2.27           | W    |
| Thermal Resistance Junction-to-Ambient (Note 3)                      | $R_{\theta JA}$                   | 69             | °C/W |
| Power Dissipation per Transistor @ T <sub>A</sub> = 25°C (Note 3)    | P <sub>D</sub>                    | 1.8            | W    |
| Junction and Storage Temperature Range                               | T <sub>J</sub> , T <sub>stg</sub> | -55 to<br>+150 | °C   |

- 1. Per JESD51-7 with 100 mm<sup>2</sup> pad area and 2 oz. Cu (Dual Operation).
- 2. P<sub>D</sub> per Transistor when both are turned on is one half of Total P<sub>D</sub> or 1.13 Watts.
- 3. Per JESD51–7 with 100 mm<sup>2</sup> pad area and 2 oz. Cu (Single–Operation).

# 60 Volt, 1 Amp PNP Low V<sub>CE(sat)</sub> Transistors

# WDFN6 CASE 506AN



**MARKING** 

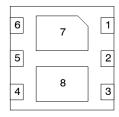
ΑP = Specific Device Code

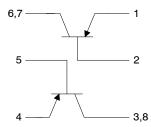
= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

#### PIN CONNECTIONS





#### ORDERING INFORMATION

| Device          | Package            | Shipping <sup>†</sup> |
|-----------------|--------------------|-----------------------|
| NSS60100DMTTBG  | WDFN6<br>(Pb-Free) | 3000/Tape &<br>Reel   |
| NSV60100DMTWTBG | WDFN6<br>(Pb-Free) | 3000/Tape &<br>Reel   |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Table 1. ELECTRICAL CHARACTERISTICS ( $T_A = 25^{\circ}C$  unless otherwise noted)

| Characteristic   | Symbol                | Min                    | Тур                        | Max                        | Unit |
|--|-----------------------|------------------------|----------------------------|----------------------------|------|
| OFF CHARACTERISTICS  |                       |                        | •                          |                            |      |
| Collector-Emitter Breakdown Voltage (I <sub>C</sub> = -10 mA, I <sub>B</sub> = 0)  | V <sub>(BR)CEO</sub>  | -60                    |                            |                            | V    |
| Collector-Base Breakdown Voltage (Ic = -0.1 mA, I <sub>E</sub> = 0)  | V <sub>(BR)CBO</sub>  | -80                    |                            |                            | V    |
| Emitter-Base Breakdown Voltage ( $I_E = -0.1 \text{ mA}, I_C = 0$ )  | V <sub>(BR)EBO</sub>  | -6                     |                            |                            | V    |
| Collector Cutoff Current (V <sub>CB</sub> = -60 V, I <sub>E</sub> = 0)   | I <sub>CBO</sub>      |                        |                            | -100                       | nA   |
| Emitter Cutoff Current (V <sub>BE</sub> = -5.0 V)  | I <sub>EBO</sub>      |                        |                            | -100                       | nA   |
| ON CHARACTERISTICS   |                       |                        |                            |                            |      |
| DC Current Gain (Note 4) $ (I_C = -100 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -1 \text{ A}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -2 \text{ A}, V_{CE} = -2.0 \text{ V}) $ | h <sub>FE</sub>       | 150<br>120<br>90<br>40 | 230<br>180<br>140<br>80    |                            |      |
| Collector–Emitter Saturation Voltage (Note 4) $ (I_C = -500 \text{ mA}, I_B = -50 \text{ mA}) $ $ (I_C = -1 \text{ A}, I_B = -50 \text{ mA}) $ $ (I_C = -1 \text{ A}, I_B = -100 \text{ mA}) $   | V <sub>CE(sat)</sub>  |                        | -0.115<br>-0.250<br>-0.200 | -0.160<br>-0.350<br>-0.300 | V    |
| Base – Emitter Saturation Voltage (Note 4) $ (I_C = -500 \text{ mA}, I_B = -50 \text{ mA}) $ $ (I_C = -1 \text{ A}, I_B = -50 \text{ mA}) $ $ (I_C = -1 \text{ A}, I_B = -100 \text{ mA}) $  | V <sub>BE</sub> (sat) |                        |                            | -1.0<br>-1.0<br>-1.1       | V    |
| Base–Emitter Turn–on Voltage (Note 4) (I <sub>C</sub> = 500 mA, I <sub>B</sub> = 50 mA)  | V <sub>BE(on)</sub>   |                        |                            | -0.9                       | V    |
| DYNAMIC CHARACTERISTICS  |                       |                        |                            | •                          | 1    |
| Output Capacitance<br>(V <sub>CB</sub> = 10 V, f = 1.0 MHz)  | C <sub>obo</sub>      |                        | 18                         |                            | pF   |
| Cutoff Frequency (I <sub>C</sub> = 50 mA, $V_{CE}$ = 2.0 V, f = 100 MHz)   | f <sub>T</sub>        |                        | 155                        |                            | MHz  |
| SWITCHING TIMES  |                       |                        |                            |                            |      |
| Delay Time ( $V_{CC}$ = -10 V, $I_{C}$ = -0.5 A, $I_{B1}$ = -25 mA, $I_{B2}$ = 25 mA)  | t <sub>d</sub>        |                        | 15                         |                            | ns   |
| Rise Time ( $V_{CC} = -10 \text{ V}, I_{C} = -0.5 \text{ A}, I_{B1} = -25 \text{ mA}, I_{B2} = 25 \text{ mA}$ )  | t <sub>r</sub>        |                        | 13                         |                            | ns   |
| Storage Time ( $V_{CC}$ = -10 V, $I_{C}$ = -0.5 A, $I_{B1}$ = -25 mA, $I_{B2}$ = 25 mA)  | t <sub>s</sub>        |                        | 360                        |                            | ns   |
| Fall Time ( $V_{CC} = -10 \text{ V}, I_{C} = -0.5 \text{ A}, I_{B1} = -25 \text{ mA}, I_{B2} = 25 \text{ mA}$ )  | t <sub>f</sub>        |                        | 22                         |                            | ns   |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Condition: Pulse Width = 300 µsec, Duty Cycle ≤ 2%

#### **TYPICAL CHARACTERISTICS**

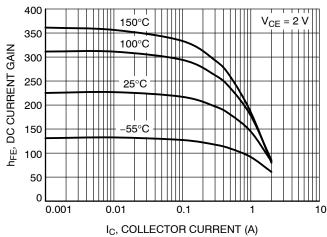


Figure 1. DC Current Gain

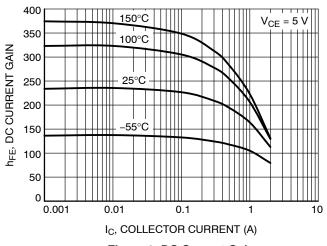


Figure 2. DC Current Gain

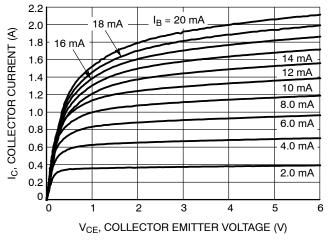


Figure 3. Collector Current as a Function of Collector Emitter Voltage

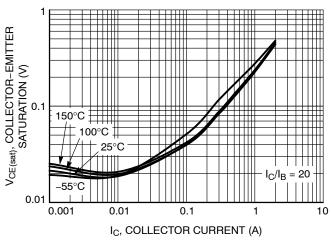


Figure 4. Collector-Emitter Saturation Voltage

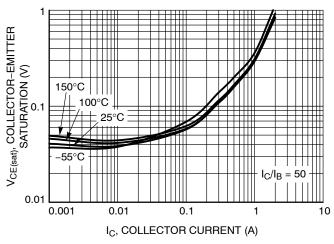


Figure 5. Collector-Emitter Saturation Voltage

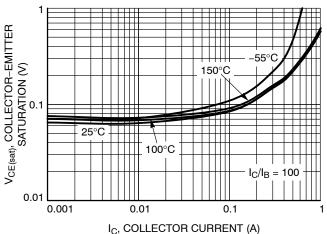
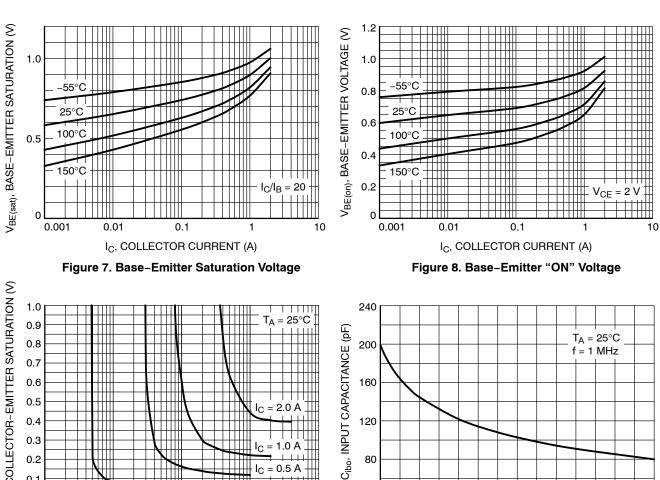
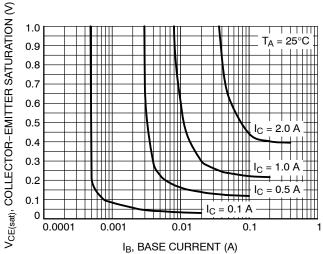


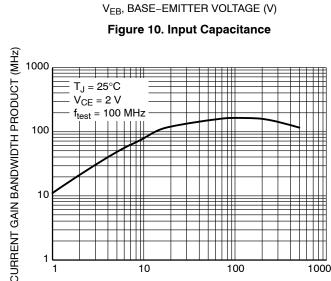
Figure 6. Collector-Emitter Saturation Voltage

#### **TYPICAL CHARACTERISTICS**









V<sub>CB</sub>, COLLECTOR-BASE VOLTAGE (V) Figure 11. Output Capacitance

= 25°C

1 MHz

f<sub>T</sub>, CURRENT GAIN BANDWIDTH PRODUCT (MHz) IC, COLLECTOR CURRENT (mA)

Figure 12. f<sub>T</sub>, Current Gain Bandwidth Product

Cobo, OUTPUT CAPACITANCE (pF)

#### **TYPICAL CHARACTERISTICS**

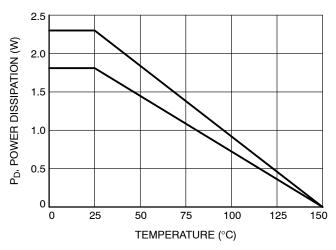


Figure 13. Power Derating

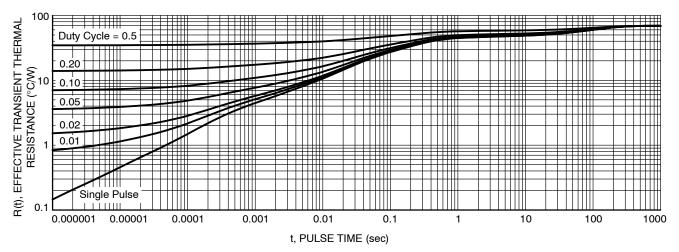


Figure 14. Thermal Resistance by Transistor

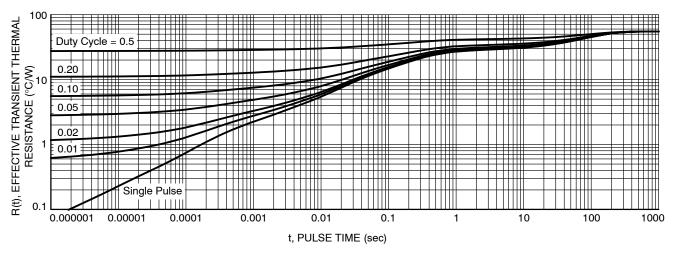


Figure 15. Thermal Resistance for Both Transistors

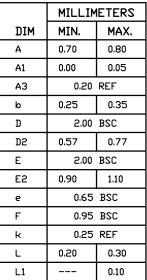


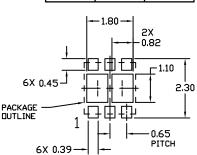


**DATE 25 JAN 2022** 

#### NOTES:

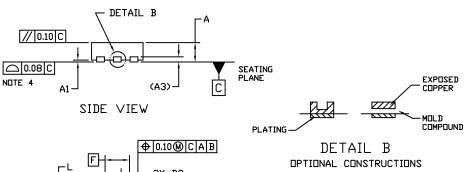
- DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSION 6 APPLIES TO PLATED
  TERMINAL AND IS MEASURED BETWEEN
  0.15 AND 0.30 MM FROM THE TERMINAL TIP.
- 4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.

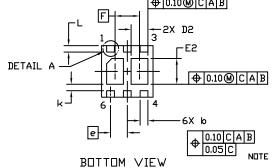




RECOMMENDED
MOUNTING FOOTPRINT
SOLDERMASK DEFINED

|                   | A             |                                 |       |
|-------------------|---------------|---------------------------------|-------|
| PIN ONE REFERENCE | B             |                                 |       |
| □0.10 C           | Į į           | L1 1 -                          | TT-FL |
| △ 0.10 C          | J<br>Top View | DETAIL A OPTIONAL CONSTRUCTIONS |       |





# GENERIC MARKING DIAGRAM\*



XX = Specific Device CodeM = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

| DOCUMENT NUMBER: | 98AON20861D      | Electronic versions are uncontrolled except when accessed directly from the Document Reposito<br>Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |             |
|------------------|------------------|--|-------------|
| DESCRIPTION:     | WDFN6 2x2, 0.65P |  | PAGE 1 OF 1 |

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